
2SC3553

Silicon NPN Epitaxial

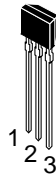
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Application

Low frequency amplifier

Outline

SPAK



- 1. Emitter
- 2. Collector
- 3. Base

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	35	V
Collector to emitter voltage	V_{CEO}	35	V
Emitter to base voltage	V_{EBO}	4	V
Collector current	I_C	500	mA
Collector power dissipation	P_C	300	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

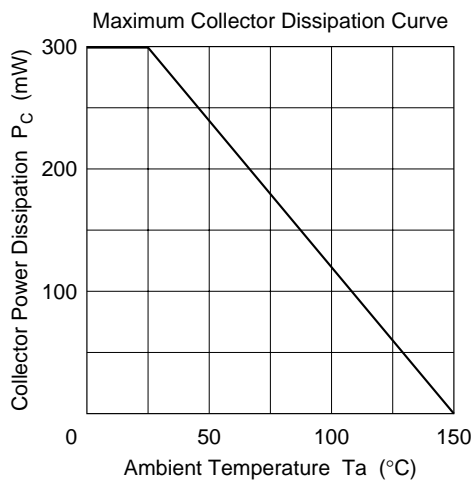
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	35	—	—	V	$I_C = 10\text{ }\mu\text{A}$, $I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	35	—	—	V	$I_C = 1\text{ mA}$, $R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	4	—	—	V	$I_E = 10\text{ }\mu\text{A}$, $I_C = 0$
Collector cutoff current	I_{CBO}	—	—	0.5	μA	$V_{CB} = 20\text{ V}$, $I_E = 0$
DC current transfer ratio	h_{FE1}^{*1}	60	—	320		$V_{CE} = 3\text{ V}$, $I_C = 10\text{ mA}$
	h_{FE2}	10	—	—		$V_{CE} = 3\text{ V}$, $I_C = 500\text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	0.2	0.6	V	$I_C = 150\text{ mA}$, $I_B = 15\text{ mA}^{*2}$
Base to emitter voltage	V_{BE}	—	0.64	—	V	$V_{CE} = 3\text{ V}$, $I_C = 10\text{ mA}$

Notes: 1. The 2SC3553 is grouped by h_{FE1} as follows.

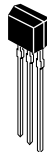
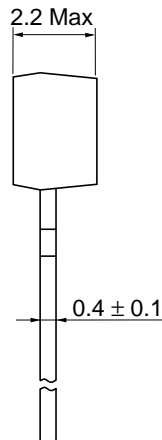
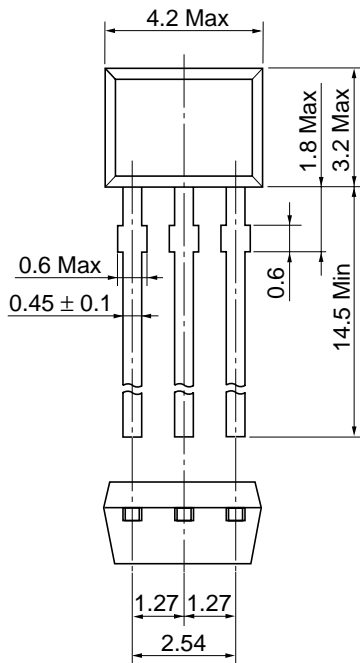
2. Pulse test

B	C	D
60 to 120	100 to 200	160 to 320

See characteristic curves of 2SC1213.



Unit: mm



Hitachi Code	SPAK
JEDEC	—
EIAJ	—
Weight (reference value)	0.10 g

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